



Material Content Data Sheet



Sales Product Name		TLE9278BQX		Issued		31. January 2019			
MA#		MA003568586							
Package		PG-VQFN-48-31		Weight*		129.86 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.524	3.48	3.48	34839	34839	
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138		
		non noble metal	zinc	7440-66-6	0.072	0.06		552	
		non noble metal	iron	7439-89-6	1.433	1.10		11036	
wire	non noble metal	copper	7440-50-8	58.193	44.82	45.99	448115	459841	
		copper	7440-50-8	0.572	0.44	0.44	4404	4404	
encapsulation	organic material	carbon black	1333-86-4	0.182	0.14		1402		
		plastics	epoxy resin	-	7.706	5.93		59338	
		inorganic material	silicondioxide	60676-86-0	52.787	40.65	46.72	406485	467225
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	19993	19993	
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4727	4727	
glue	plastics	epoxy resin	-	0.268	0.21		2063		
		noble metal	silver	7440-22-4	0.897	0.69	0.90	6908	8971
*deviation	< 10%				Sum in total:		100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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